

3A Snubber Damping Rectifier

DIS0365CH

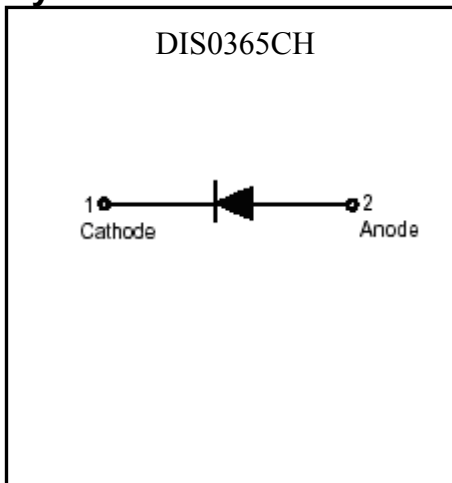
Features

- High current capability
- Smoothly soft reverse recovery time (trr)
- Low profile surface mounted package in order to minimize board space
- Pb-free lead plating and halogen-free package

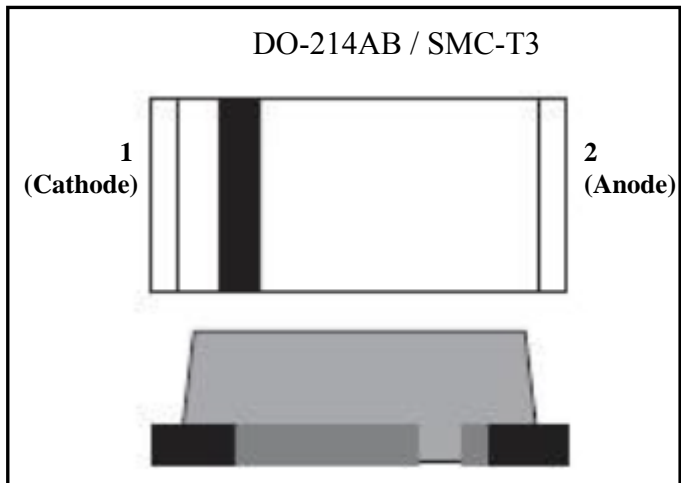
Mechanical data

- Case : Molded plastic, JEDEC DO-214AB / SMC-T3
- Epoxy : UL94-V0 rated flame retardant
- Terminals : Plated terminals, solderable per MIL-STD-750 method 2026
- Polarity : Indicated by cathode band
- Mounting position : Any
- Weight: 0.1443gram

Symbol

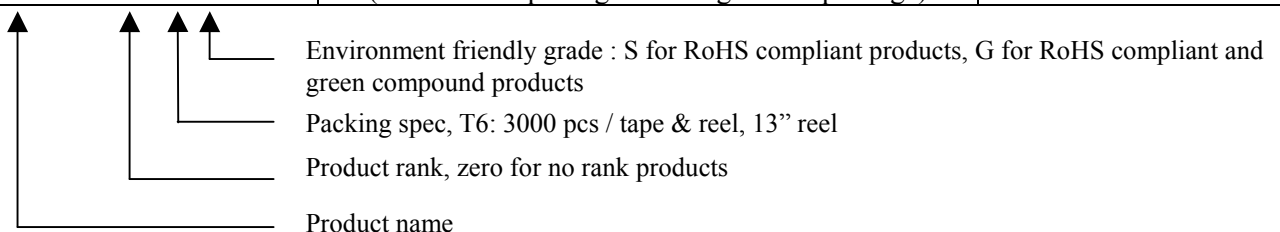


Outline



Ordering Information

Device	Package	Shipping
DIS0365CH-XX-T6-G	SMC (Pb-free lead plating and halogen-free package)	3000 pcs / tape & reel





Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$, unless otherwise noted)

Parameters	Conditions	Symbol	Value	Units
Repetitive peak reverse voltage		VRRM	650	V
RMS voltage		VRMS	455	V
Continuous reverse voltage		VR	650	V
Forward rectified current	Single phase half wave, 60Hz @ $T_J=25^{\circ}\text{C}$	IF(AV)	3	A
Repetitive Peak Forward Current	Single phase half wave, 60Hz @ $T_J=25^{\circ}\text{C}$	IFRM	4.7	A
Forward surge current	8.3ms single half sine-wave superimposed on rated load (JEDEC method)	IFSM	45	A
Maximum reverse recovery time	IF=1A, dIF/dt=100A/ μs	trr	1	μs
Power Dissipation	$T_A=25^{\circ}\text{C}$ (Note)	PD	3.6	W
	$T_A=70^{\circ}\text{C}$ (Note)		2.3	
	$T_C=25^{\circ}\text{C}$		15.6	
	$T_C=100^{\circ}\text{C}$		6.2	
Storage temperature range		Tstg	-55~+150	$^{\circ}\text{C}$
Operating junction temperature range		Tj	-55~+150	$^{\circ}\text{C}$

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	Rth,j-c	8	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-ambient, max (Note)	Rth,j-a	35	

Note : Mounted on PCB with 30mmx30mm copper pad area.

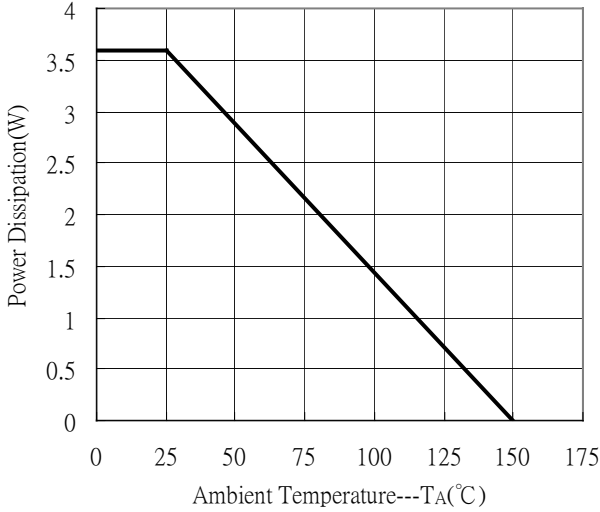
Characteristics ($T_A=25^{\circ}\text{C}$, unless otherwise noted)

Characteristic	Symbol	Condition	Min.	Typ	Max.	Unit
Continuous reverse voltage	VR	IR=100 μA	650	-	-	V
Forward Voltage	VF 1	IF=1A	-	-	1.1	V
	VF 2	IF=3A	-	-	1.2	
Reverse Leakage Current	IR	VR=620V	-	-	100	nA
		VR=540V, $T_A=125^{\circ}\text{C}$	-	-	10	μA
Junction Capacitance	CJ	VR=1V, f=1MHz	-	48	-	pF

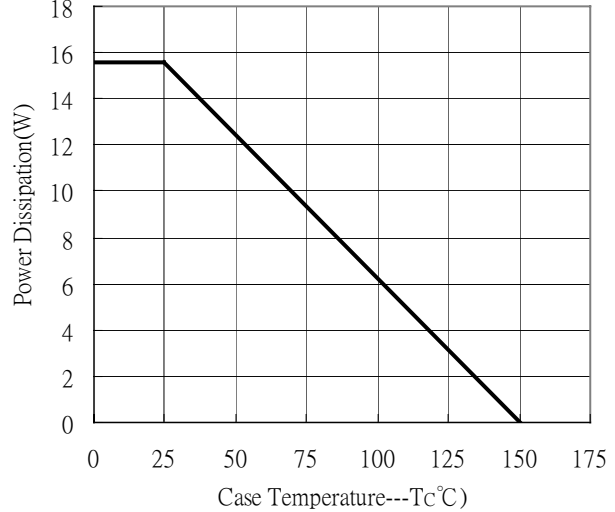


Typical Characteristics

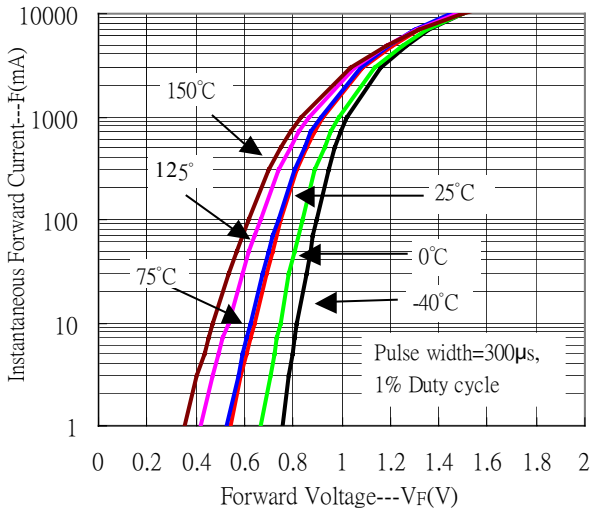
Power Derating Curve



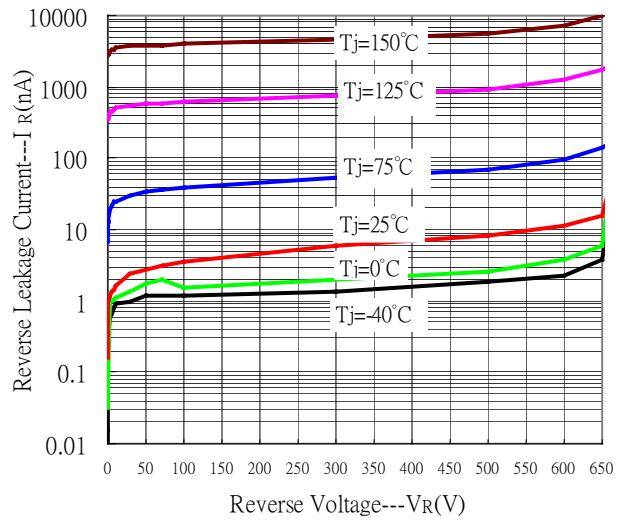
Power Derating Curve



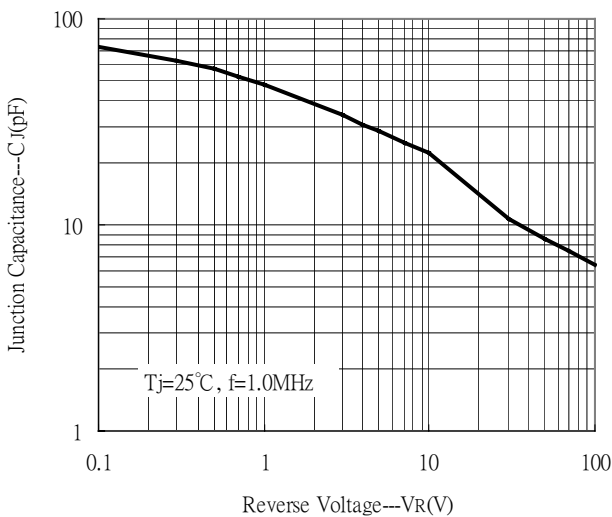
Forward Current vs Forward Voltage



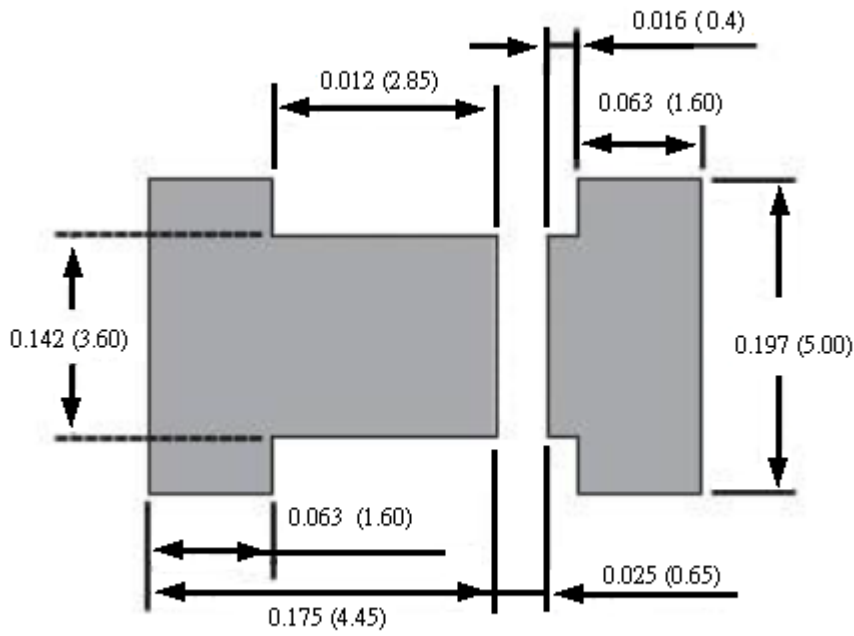
Reverse Leakage Current vs Reverse Voltage



Junction Capacitance vs Reverse Voltage

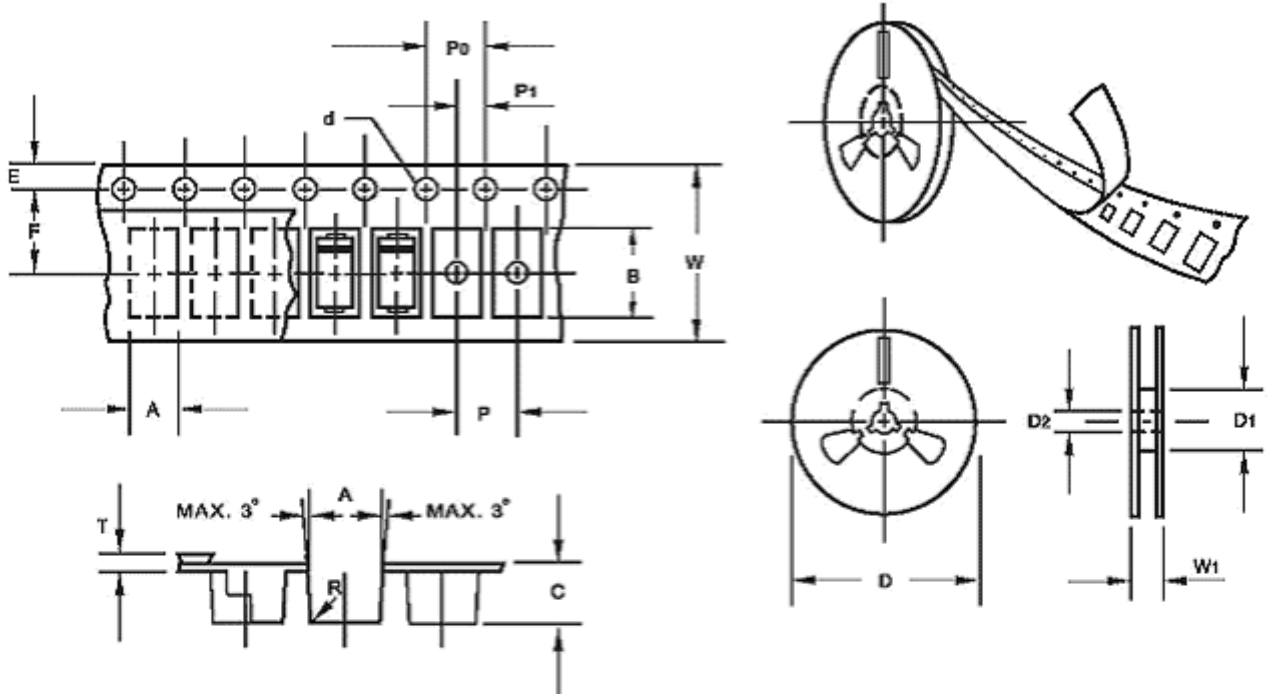


Recommended Footprint



Dimensions in inches (millimeter)

Taping Reel Dimension



unit : mm

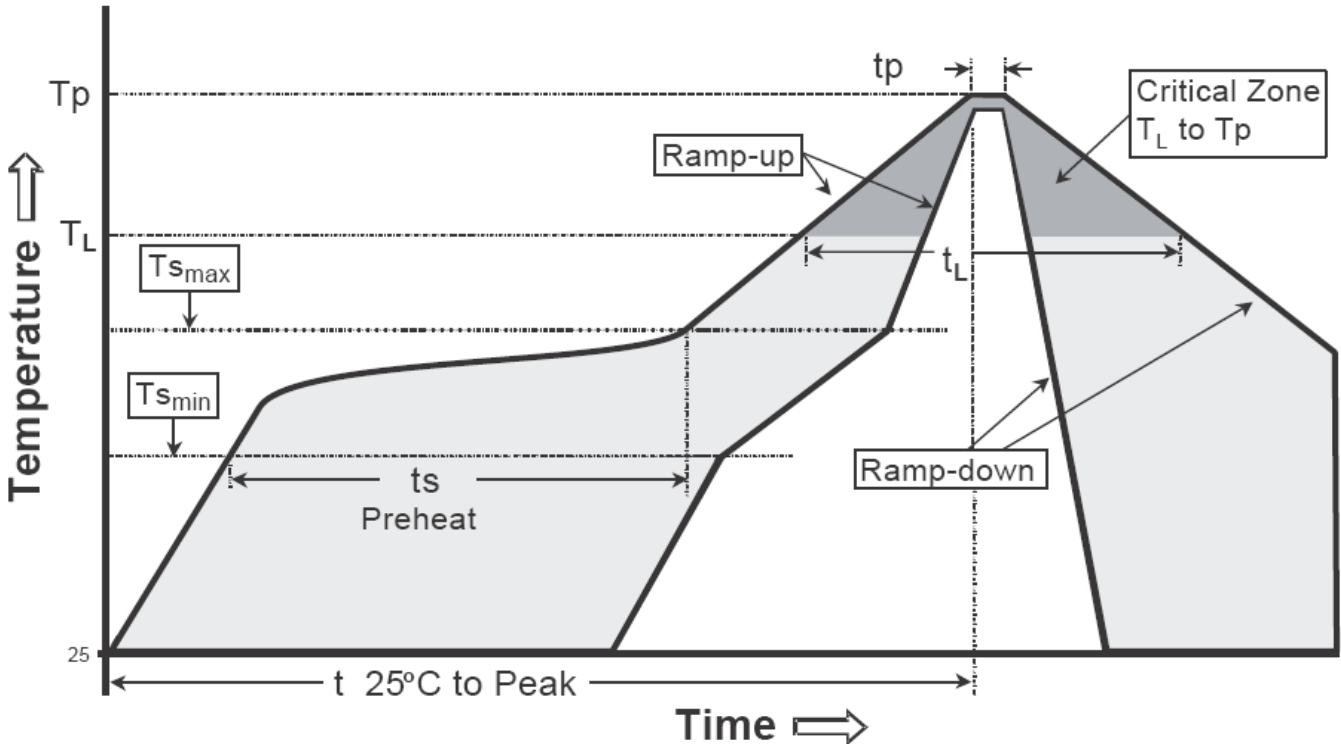
Item	Tolerance	Symbol	
Carrier width	0.10	A	4.85
Carrier length	0.10	B	6.95
Carrier depth	0.10	C	1.85
Sprocket hole	0.10	d	1.50
Reel outside diameter	2.00	D	330.00
Reel inner diameter	min.	D1	50.00
Feed hole diameter	0.50	D2	13.00
Sprocket hole position	0.10	E	1.75
Punch hole position	0.10	F	5.50
Punch hole pitch	0.10	P	8.00
Sprocket hole pitch	0.10	P0	4.00
Embossment center	0.10	P1	2.00
Overall tape thickness	0.10	T	0.23
Tape width	0.30	W	12.00
Reel width	1.00	W1	18.00

Note : Devices are packed in accordance with EIA standard RS-481-A and specification given above.

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

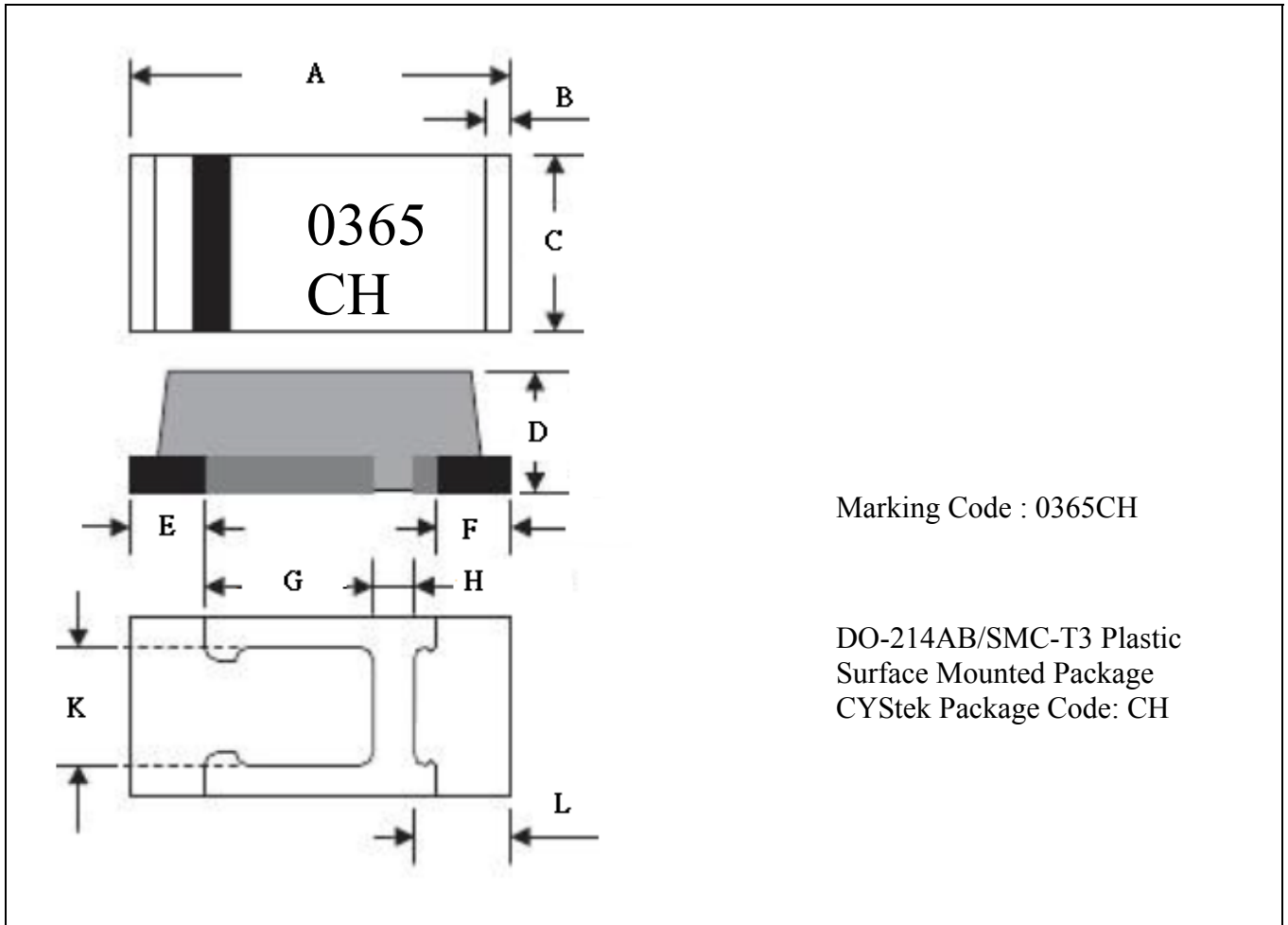
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (Tl)	183°C	217°C
- Time (tl)	60-150 seconds	60-150 seconds
Peak Temperature(Tp)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note :1. All temperatures refer to topside of the package, measured on the package body surface.
 2.For devices mounted on FR-4 PCB of 1.6mm or equivalent grade PCB. If other grade PCB is used, care should be taken to match the coefficients of thermal expansion between components and PCB. If they are not matched well, the solder joints may crack or the bodies of the parts may crack or shatter as the assembly cools.

DO-214AB / SMC-T3 Dimension



Marking Code : 0365CH

DO-214AB/SMC-T3 Plastic
 Surface Mounted Package
 CYStek Package Code: CH

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.248	0.264	6.30	6.70	F	0.047	TYP	1.20	TYP
B	0.020	TYP	0.50	TYP	G	0.104	0.120	2.65	3.05
C	0.170	0.185	4.30	4.70	H	0.026	0.041	0.65	1.05
D	0.059	0.067	1.50	1.70	K	0.126	0.142	3.20	3.60
E	0.047	TYP	1.20	TYP	L	0.063	TYP	1.60	TYP

Notes : 1.Controlling dimension : millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

- Lead : Pure tin plated.
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0.

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